

SCCM Series

Features

Powerful components with composite co-fired material to solve EMI problem for high speed differential signal transmission line as USB, and LVDS without distortion to high speed signal transmission.

Applications

MIPI, MHL serial interface in mobile device.

Product Identification

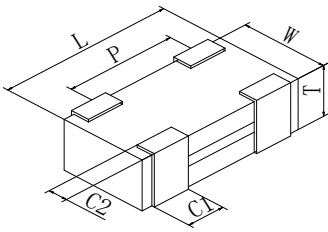
SCCM XXXXXTL - XXX
For example:SCCM321610TL-900

General Specifications

Test Frequency.....100MHz
Parameters Test Temp..... 25℃
Operation Temp.....-20℃ to +85℃
(Including temperature Rise)
Storage Temp.....0~40℃
Storage Humidity.....<70% RH
Resistance to Soldering Heat.....260℃ for 10 sec
Temperature Rise.....40℃ Typ. at Rated Current

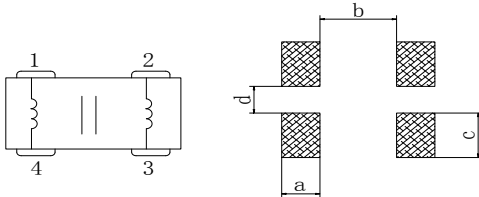
Shape And Dimensions

Dimensions In mm



TYPE	L	W	T	P	C1	C2	a	b	c	d
	±0.2	±0.2	±0.1	±0.2	±0.2	±0.2	Ref	Ref	Ref	Ref
321610	3.20	1.60	1.00	2.10	0.70	0.30	0.70	1.40	1.00	0.60

Electrical Schematic & PAD Layout



Standard Specifications

Stamp	Impedance (Ω)±25%	Test Frequency (MHz)	DCR (Ω)Max	Rated Current (mA) Max	Rated Voltage (V)	Withstand Voltage (V)	Insulation Resistance Min.(MΩ)
SCCM321610TL-900	90	100	0.50	500	10	25	200
SCCM321610TL-121	120	100	0.50	500	10	25	200

*All the data listed in this catalogue are for reference only, JENG SHI reserves the right to alter or revise the specifications without prior notification.

*Beyond the above specification also can meet the special requirements. Need detailed content Please to the website query or contact us.

